Filename: PMP9751_BOM.xls

Variant: None

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PMP9751 Bill Of Material

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C100	1	150uF	CAP, TANT, 150uF, 6.3V, +/-10%, 0.07 ohm, 7343-20 SMD	7343-20	T495V157K006ATE070	Kemet
C105	1	1.5uF	CAP, CERM, 1.5uF, 6.3V, +/-20%, X5R, 0402	0402	GRM155R60J155ME80D	MuRata
C201, C205, C209	3	1.5uF	CAP, CERM, 1.5uF, 6.3V, +/-20%, X5R, 0402	0402	GRM155R60J155ME80D	MuRata
C107, C108, C109	3	10uF	CAP, CERM, 10F, 6,3V, +/-20%, X5R 0603	0603	GRM188R60J106ME84	MuRata
C203, C207, C10	3	3.3nF	CAP, CERM, 3.3nF, +/-10%, SMD	0201	500R07W332KV4T	Johanson Dielectrics
C204, C208, C212	3	15pF	CAP, CERM, 15pF, +/-5%, SMD	0201	500R07N150JV4T	Johanson Dielectrics
FB204	1		2A Ferrite Bead, 50mOhm DCR	0603	BLM18PG121SN1	MuRata
J101	1		Header, TH, 100mil, 20x1, Gold plated, 230 mil above insulator	TSW-120-07-G-S	TSW-120-07-G-S	Samtec, Inc.
J102, J103, J104	3		Header, TH, 100mil, 3x1, Gold plated, 230 mil above insulator	TSW-103-07-G-S	TSW-103-07-G-S	Samtec, Inc.
J106	1		Connector, SMA Jack, Vertical, Gold, SMD	SMA	142-0711-201	Emerson Network Power
J201, J202, J203,	15		Connector, SMT, End launch SMA 50 ohm	SMA End Launch	142-0701-851	Emerson Network Power
J204, J205, J206,						
J207, J208, J209,						
J210, J211, J212,						
J213, J214, J215						
L1	1	470nH	Inductor, Chip, 0.47uH, 4.7A, 29 mOhm, SMD	2520	DFE252012C	TOKO
R12, R13, R14	3	2.2k	RES, 2.2k ohm, 5%, 0.1W, 0603	0603	RC0603JR-072K2L	Yageo America
R15	1	49.9	RES, 49.9 ohm, 0.1%, 0.1W, 0603	0603	RT0603BRD0749R9L	Yageo America
U21	1		SKY77629 Multiband Multimode Power Amplifier Module for Quad-	MCM, 5x1x7mm	SKY77629	Skyworks Solutions
			Band GSM/ EDGE, Hexa-Band (I, II, III, IV, V, VIII) WCDMA/ HSDPA/			
			HSUPA/ HSPA+/ LTE			
U101	1		Low-, Wide- Voltage Battery Front-End DC/DC Converter Single-Cell	YFF0016AEAE	TPS61280YFF	Texas Instruments
			Li-Ion, Ni-Rich, Si-Anode Applications, YFF0016AEAE			

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